

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4	9.40mil	4.8	
5	Mid-Layer 1	Copper	2.80mil		
6	Dielectric2	FR-4	9.00mil	4.8	
7	Mid-Layer 2	Copper	2.80mil		
8	Dielectric3	FR-4	9.40mil	4.8	
9	Bottom Layer	Copper	2.80mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER 39.8 MIL
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

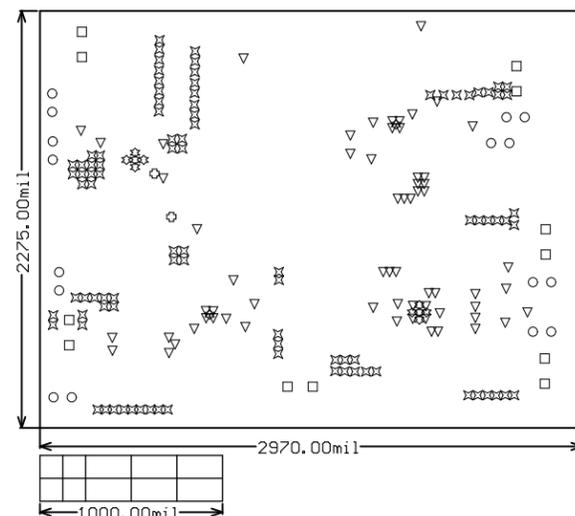
ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
⊛	12	7.67mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	2	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
▽	64	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	92	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
○	16	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	12	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
	198 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.
LAYER NAME = PCB Fabrication Drawing	TID #: TIDA-00804			
PLOT NAME = Fabrication Drawing	GENERATED : 3/8/2016 2:43:37 PM	TEXAS INSTRUMENTS		

TEXAS INSTRUMENTS

PROJECT TITLE:
Automotive i.MX6Q Power Solution

DESIGNED FOR:
Public Release

FILE NAME:
PMP4442-Pcb.PcbDoc

ENGINEER:
David Ji

LAYOUT BY:
David Ji

SCALE: 1.00

ALTIM DESIGNER VERSION:
16.0.8.354

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